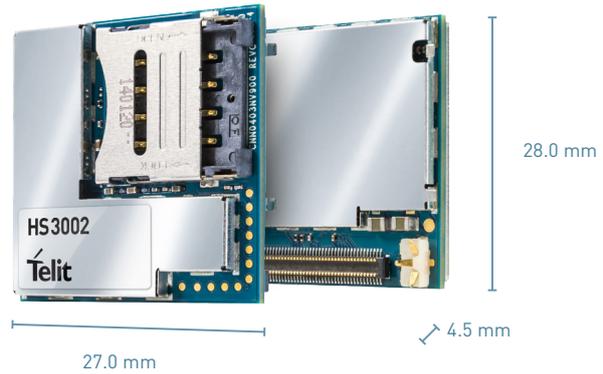


## HS3002

UMTS | HSDPA 3.6 Connectorized



### Product description

The HS 3002 is a Qualcomm® chipset-based HSDPA (UMTS 3G) cellular module with a 100-pin Molex® I/O and Board-to-Board (B2B) RF connectors. This module will excel in applications requiring low power consumption, extended temperatures, multiple radio choices, and optional audio support. With dual-band HSDPA (UMTS 3G) and GPRS/EDGE radios available in two SKUs and optional SIM, the HS 3002 is designed to meet your global integration objectives. The HS 3002 is certified with AT&T, PTCRB, GCF, and other regulatory bodies for international use.

### Profiles

The modular architecture is shared across all platforms and powered by a programmable rules engine. The network router, control, and automation capabilities provide manufacturers with a flexible structural design for rapid product development and deployment.

This Module preserve the same 100-pin I/O and B2B RF connectors in the HS300x series; a compatible x-y size and mounting; and the same firmware API. Another benefit of an HS300x family transition is that you can even reuse most of your valuable script features. This compatibility allows a single design and integration effort to support worldwide deployments across multiple carriers.

### Key Benefits

- Leading-edge silicon solutions from Qualcomm
- 100-pin connector form factor is compatible across technologies
- SIM carrier provides smallest overall system size
- SMS
- Voice
- Packet Data
- TCP/IP and UDP/IP software stack with Packet Assembler Disassembler
- Network router and control/automation

# HS3002

	HS3002-NA	HS3002-EU	HS3002-AU
<b>Market</b>	North America	EMEA / APAC	EMEA / APAC
HSPA Upload (Mbps)	3.6	3.6	3.6
HSPA Download (Mbps)	3.6	3.6	3.6
<b>Frequencies</b>			
UMTS   HSPA+ bands (MHz)	850 / 1900	900 / 2100	850 / 2100
GPRS   EDGE Dual-band	850 / 1900	900 / 1800	900 / 1800
<b>Features</b>			
Data	•	•	•
Voice	•	•	•

## Product Features

- Supported bands
- NA variants:
  - 2 Bands GSM | GPRS | EDGE 850/1900 MHz
  - 2 Bands UMTS | HSPA 850/1900 MHz
- EU variants:
  - 2 Bands GSM | GPRS | EDGE 900/1800 MHz
  - 2 Bands UMTS | HSPA 900/2100 MHz
- AU variants:
  - 2 Bands GSM | GPRS | EDGE 900/1800 MHz
  - 2 Bands UMTS | HSPA 850/2100 MHz
- Integrated Micro SIM-chip or Remote 1.8/3V SIM
- Digital or Analog voice and SMS

## Data

### HSDPA category 6 in up/downlink

- Uplink up to 3.6 Mbps
- Downlink up to 3.6 Mbps

### UMTS

- Uplink/Downlink up to 384 kbps

### EDGE | GPRS category 12 in up/downlink

- Uplink up to 233.6 kbps
- Downlink up to 233.6 kbps

## SMS

- Text
- PDU
- MO/MT
- Cell Broadcast

## Physical & Environmental

- Dimensions: 28.0 x 27.0 x 4.5 mm
- Operating temperature: -30°C to +70°C
- Compliant temperature: -20°C to +60°C
- Storage temperature: -40°C to +85°C

## Interfaces

- 100-Pin Molex I/O
- B2B RF
- USB 2.0 HS
- UART
- Remote 1.8/3V SIM interface

## Approvals

- CE, GCF (HS3002-EU)
- IC, PTCRB, AT&T, FCC (HS3002-NA)
- Telstra (HS3002-AU)

## Sensitivity

- -111 dBm @ UMTS
- -109 dBm @ GSM 850 / 900 MHz
- -110 dBm @ DCS1800 / PCS1900 MHz
- Supply voltage
  - Nominal: 3.9 VDC
  - Range: 3.4 - 4.4 VDC

## Drivers

- Linux USB Drivers
- Windos-based USB Drivers



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